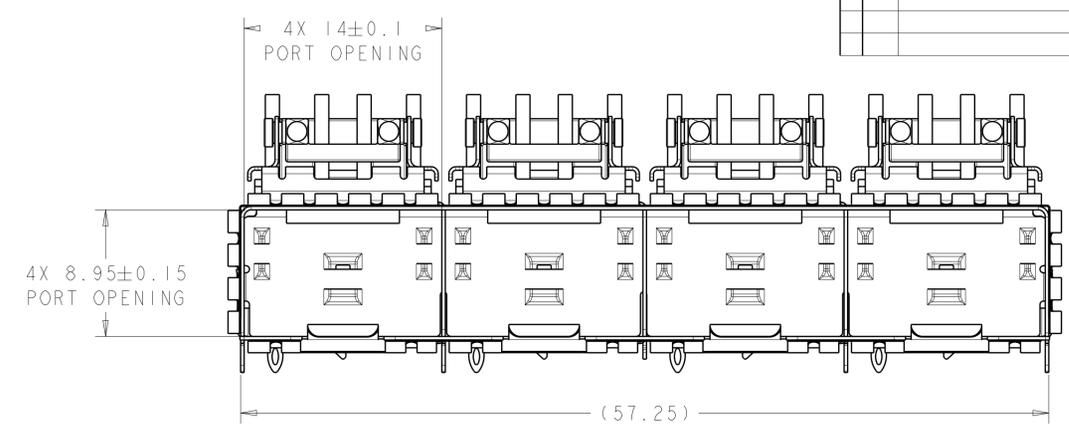
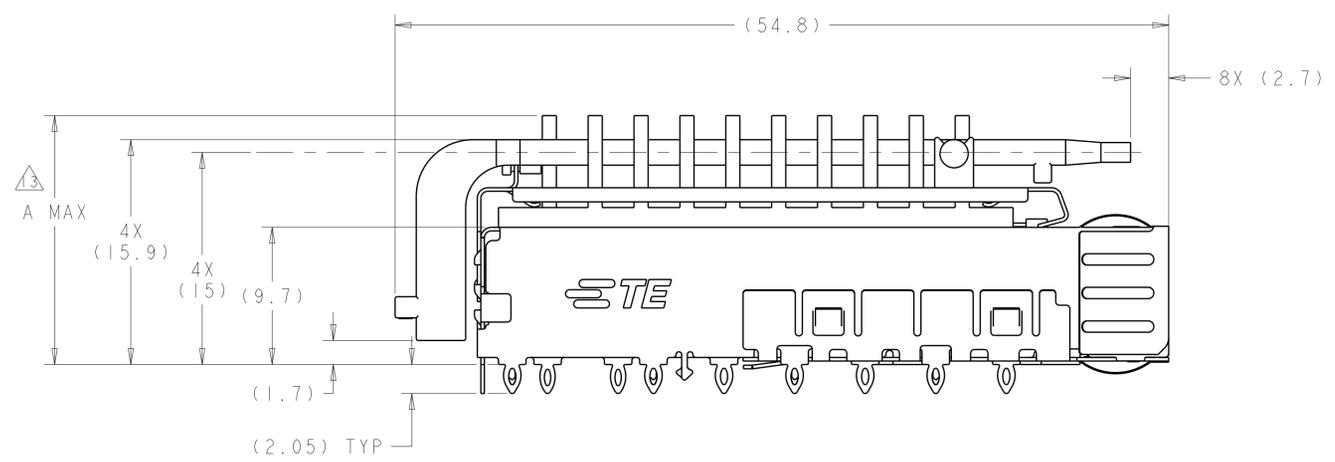
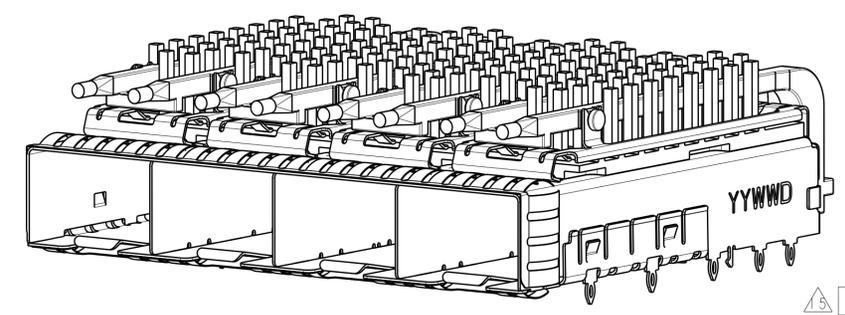
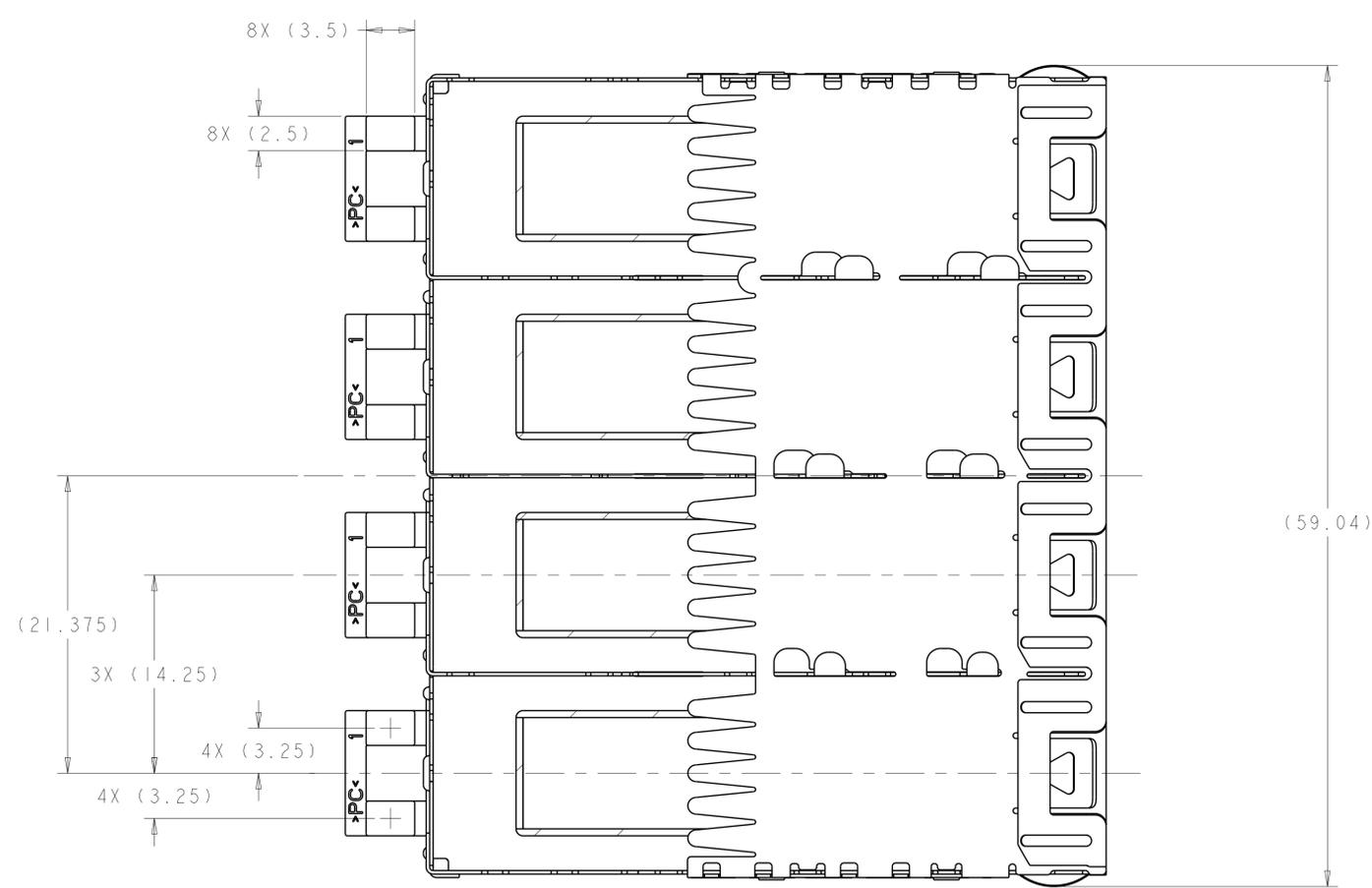


LOC		DIST		REVISONS			
P	LTN	DESCRIPTION	DATE	DWN	APVD		
I		ORIGINAL	15NOV2011	BMM	MRS		



- 1 MATERIAL:
 CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY
 HEATSINK/LIGHTPIPE CLIP: STAINLESS STEEL
 LIGHTPIPE: POLYCARBONATE, CLEAR
 HEATSINK: ALUMINUM
- 2 FINISH:
 SPRINGS: MINIMUM OF 0.8um TIN PLATE OVER A MINIMUM OF 0.8um NICKEL UNDERPLATE.
 NON-PLATED EDGES PERMISSIBLE.
 HEATSINK/LIGHTPIPE CLIP: PASSIVATE.
 HEATSINK: ELECTROLESS NICKEL.
- 3 PADS AND VIAS CHASSIS GROUND.
- 4 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 5. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 6. INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OF ASME Y14.5M-1994.
- 7 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 8 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 9 HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 14.25mm.
- 10 MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED = 1.50mm
 DOUBLE SIDED = 2.25mm
- 11. CERTAIN MATING TRANSCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD BE DETERMINED BY THE CUSTOMER.
- 12. PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- 13 DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE
- 14 HEATSINK, HEATSINK CLIP, AND LIGHTPIPE SHIPPED UNASSEMBLED TO CAGE ASSEMBLY. CAGE ASSEMBLY TO BE PRESSED INTO PCB PRIOR TO ATTACHING HEATSINK, HEATSINK CLIP, AND LIGHTPIPE TO THE CAGE ASSEMBLY.
- 15 PACKAGED AS A COMPLETE ASSEMBLY.



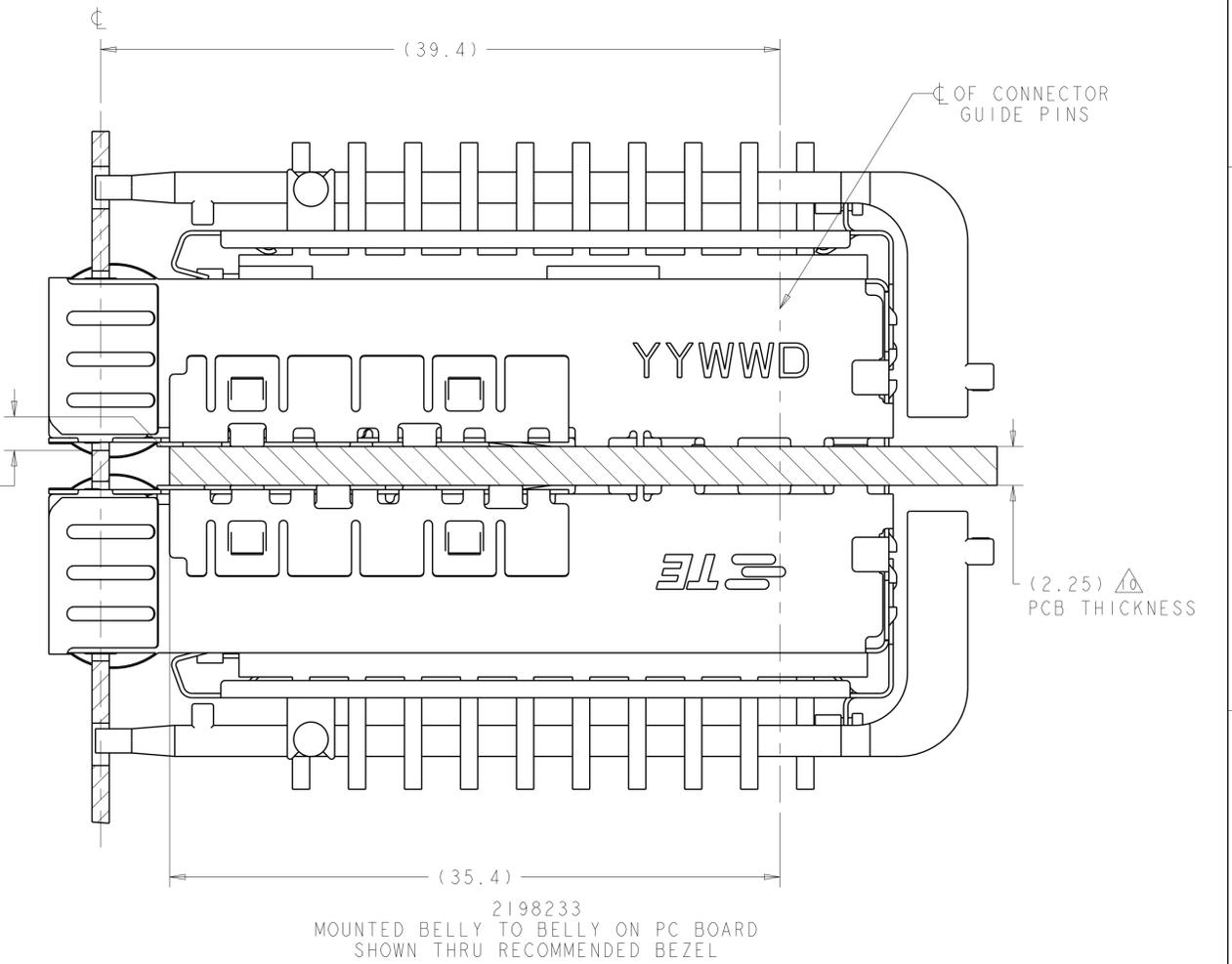
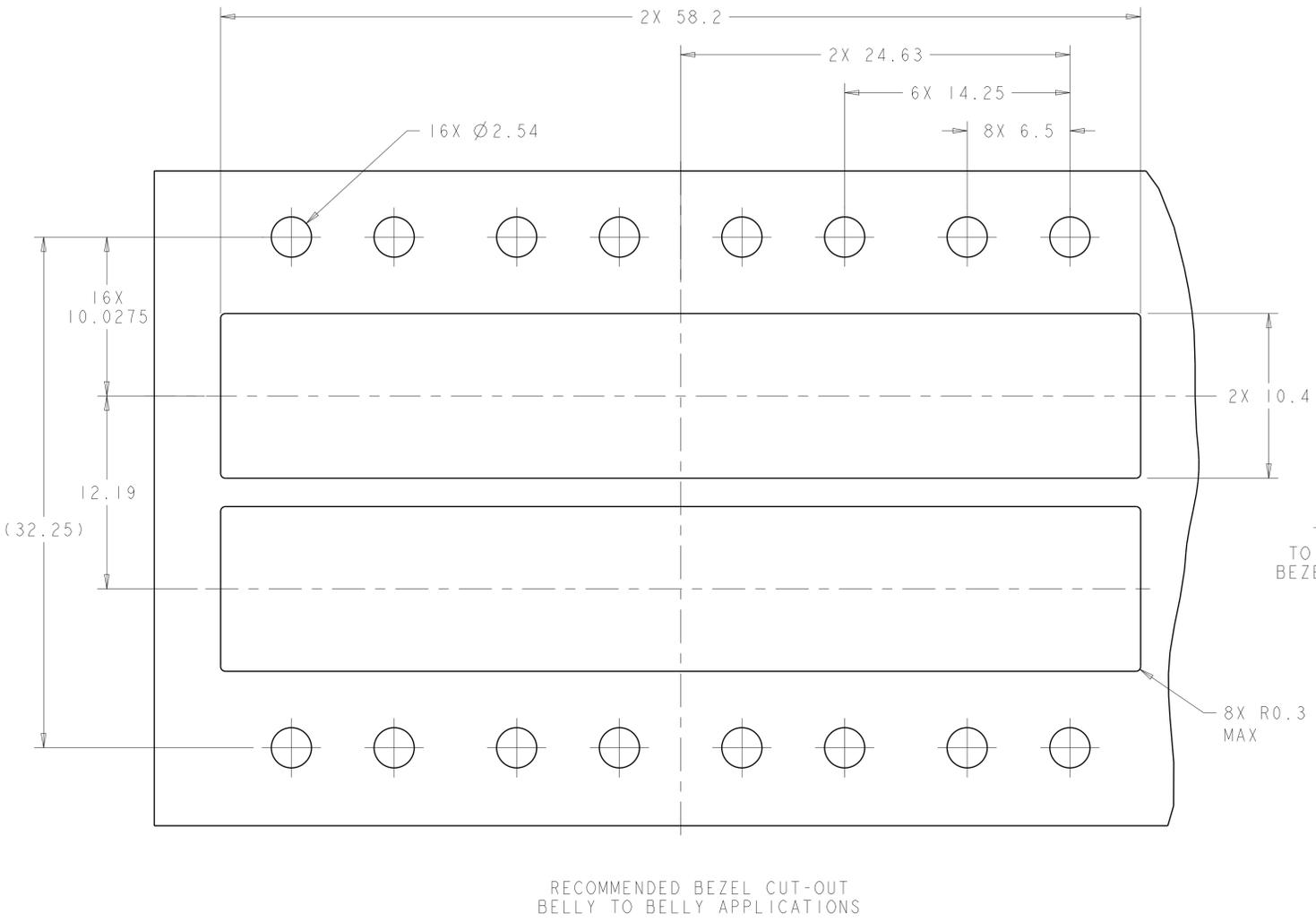
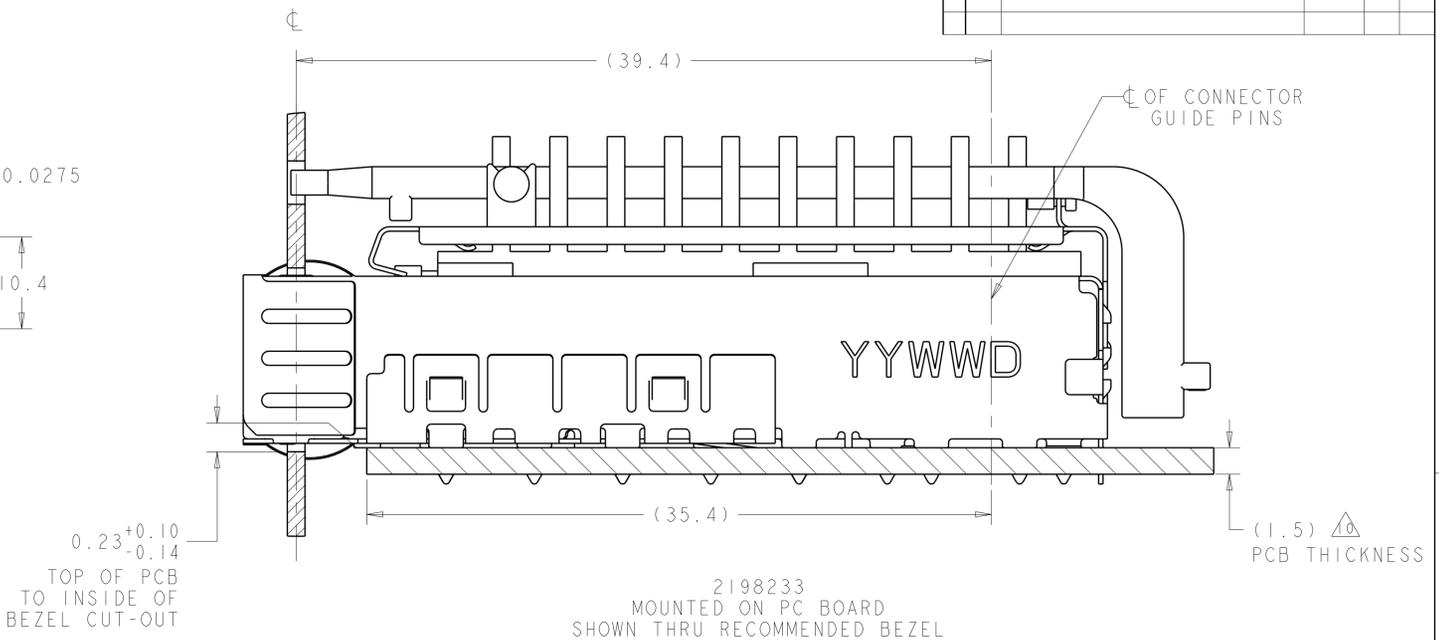
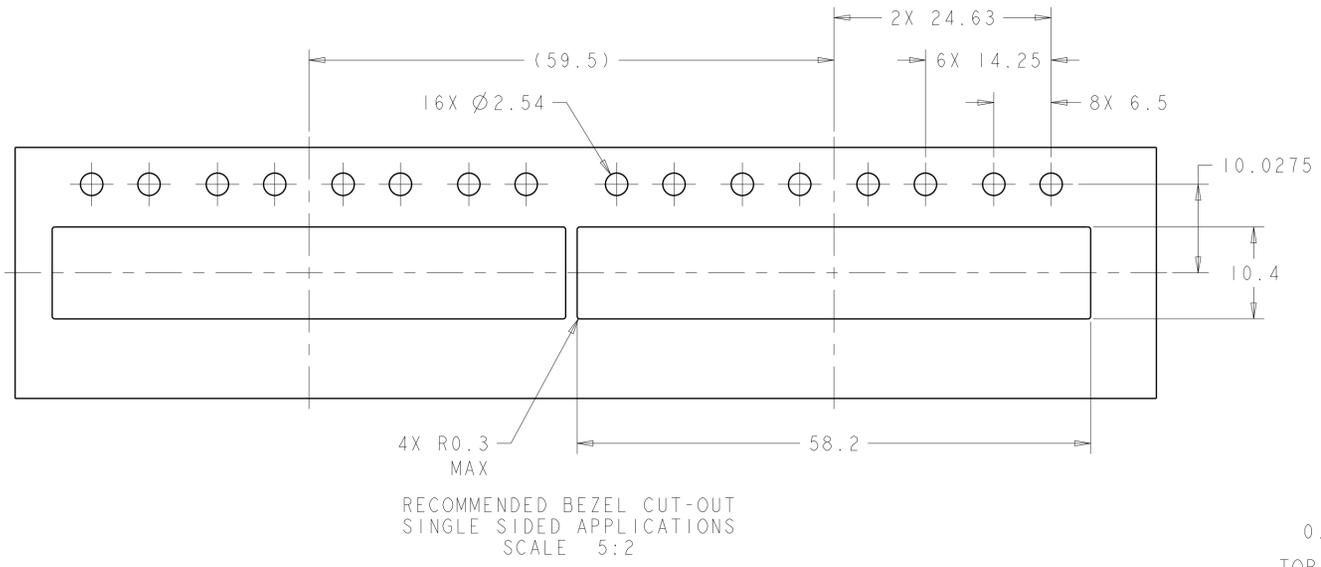
2198233
 FINISHED ASSEMBLY
 SCALE 3:1

22.5	NETWORKING, TALL	2198233-4
18.1	NETWORKING, SHORT	2198233-3
15.5	SAN	2198233-2
13.2	PCI	2198233-1
A MAX	APPLICATION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS 15NOV2011	TE Connectivity
DIMENSIONS: mm		CHK M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD M. SCHMITT 15NOV2011	NAME SFP+ ENHANCED 1X4 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE
0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±1°		PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120 WEIGHT -	
MATERIAL		FINISH	SIZE CAGE CODE DRAWING NO A100779C=2198233 RESTRICTED TO Customer Drawing
		SCALE 4:1	SHEET 1 OF 4 REV A1

LOC	DIST	REV	DATE	BY	APPV
GP	00				

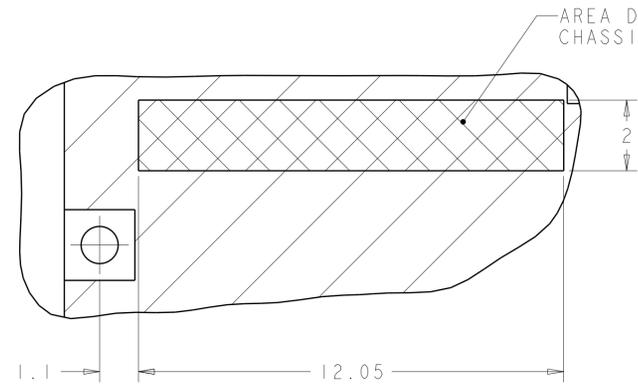
REVISIONS			
NO.	DESCRIPTION	DATE	BY
1	SEE SHEET 1		



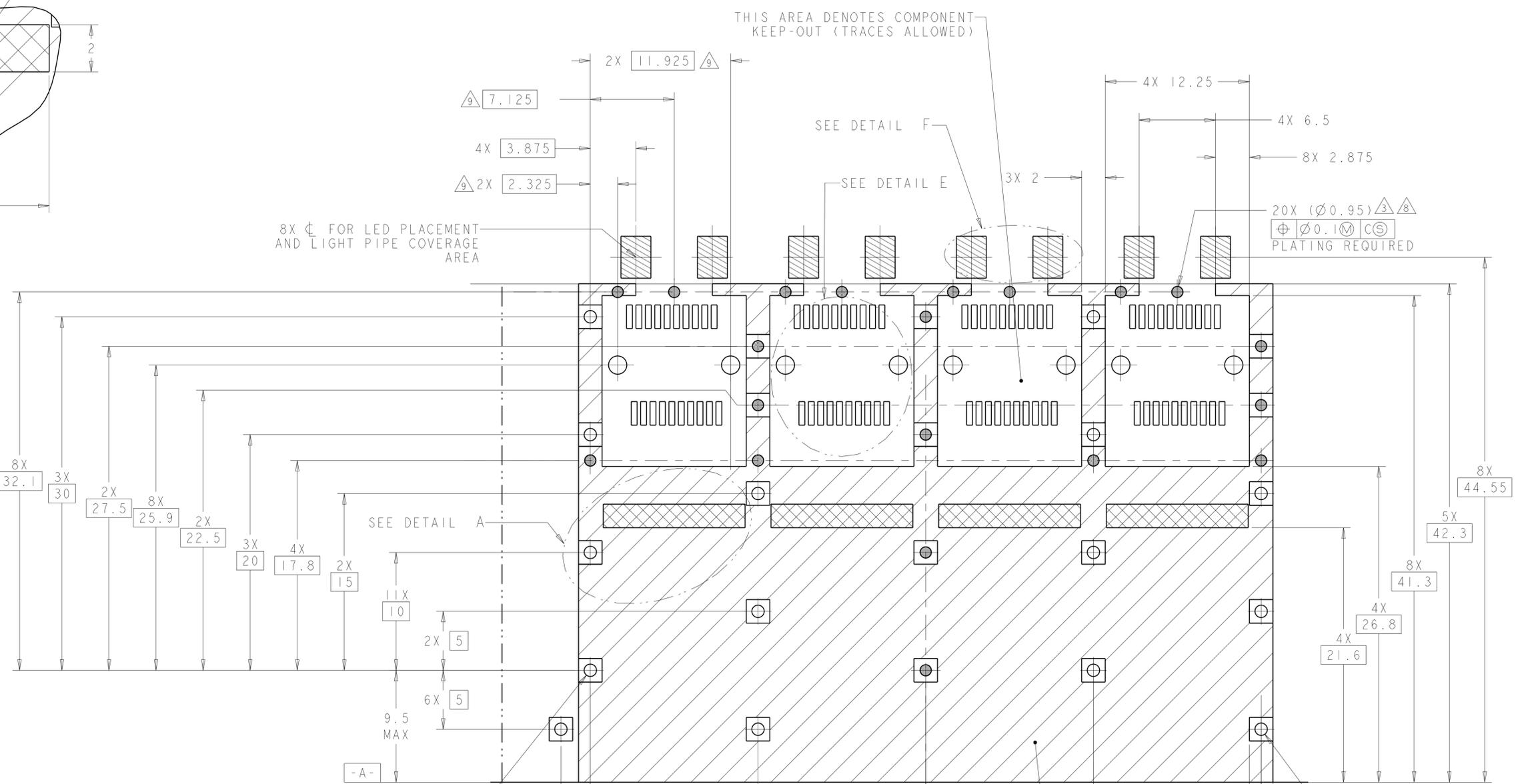
THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN B. MATTHEWS 15NOV2011	15NOV2011	 TE Connectivity
DIMENSIONS:		CHK M. SCHMITT 15NOV2011	15NOV2011	
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD M. SCHMITT 15NOV2011	15NOV2011	NAME SFP+ ENHANCED 1X4 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE
	0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±0.1	PRODUCT SPEC 108-2364 APPLICATION SPEC	SIZE 114-13120	
MATERIAL	FINISH	WEIGHT	RESTRICTED TO	A100779C=2198233 Customer Drawing SCALE 4:1 SHEET 2 OF 4 REV A1

LOC	DIST	REV	DATE	APPD
GP	00			

REVISIONS				
NO.	DESCRIPTION	DATE	BY	APPD
-	SEE SHEET 1	-	-	-



DETAIL A
 4X INDIVIDUALLY
 SCALE 10:1



8X FOR LED PLACEMENT
 AND LIGHT PIPE COVERAGE
 AREA

THIS AREA DENOTES COMPONENT
 KEEP-OUT (TRACES ALLOWED)

SEE DETAIL A

SEE DETAIL F

SEE DETAIL E

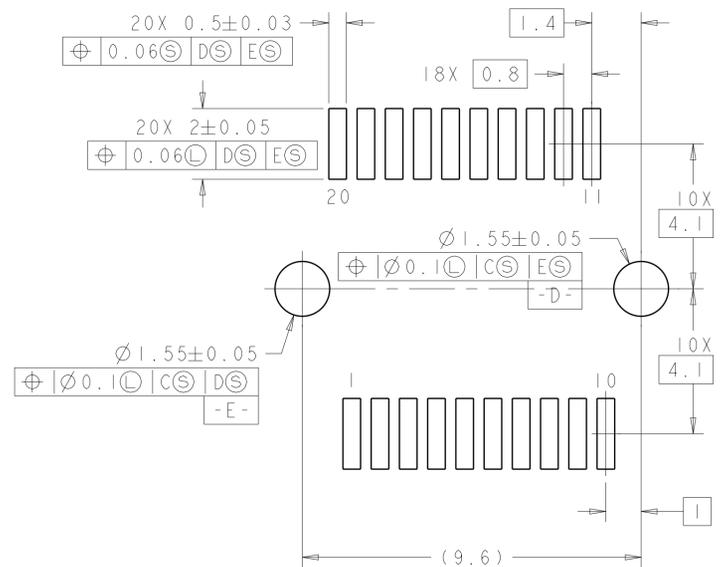
20X (Ø0.95)
 Ø0.10 CS
 PLATING REQUIRED

(Ø1.05)
 Ø0.10 AB
 PLATING REQUIRED
 -C-

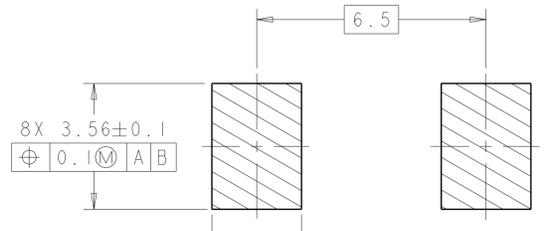
(Ø1.05)
 Ø0.10 CS
 PLATING REQUIRED

RECOMMENDED PCB CONFIGURATION
 WITH KEEP-OUT AREAS
 SINGLE SIDED APPLICATIONS
 SCALE 5:1

CROSS-HATCHED AREA DENOTES
 COMPONENT AND TRACE KEEP-OUT
 (EXCEPT CHASSIS GROUND)



DETAIL E
 RECOMMENDED PT CONNECTOR LAYOUT
 4X INDIVIDUALLY
 SCALE 10:1



DETAIL F
 SCALE 10:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: B. MATTHEWS 15NOV2011	 TE Connectivity
DIMENSIONS: mm		CHK: M. SCHMITT 15NOV2011	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: M. SCHMITT 15NOV2011	NAME: SFP+ ENHANCED 1X4 CAGE ASSEMBLY, PRESS FIT, EXTERNAL EMI SPRINGS WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC: 108-2364 APPLICATION SPEC: SIZE: 114-13120 WEIGHT: CUSTOMER DRAWING
0 PLC ±0.1		RESTRICTED TO:	
1 PLC ±0.1		SCALE: 4:1	
2 PLC ±0.1		SHEET 3 OF 4	
3 PLC ±0.1		REV: A1	
4 PLC ±0.1			
ANGLES ±1°			
FINISH: #1			

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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